

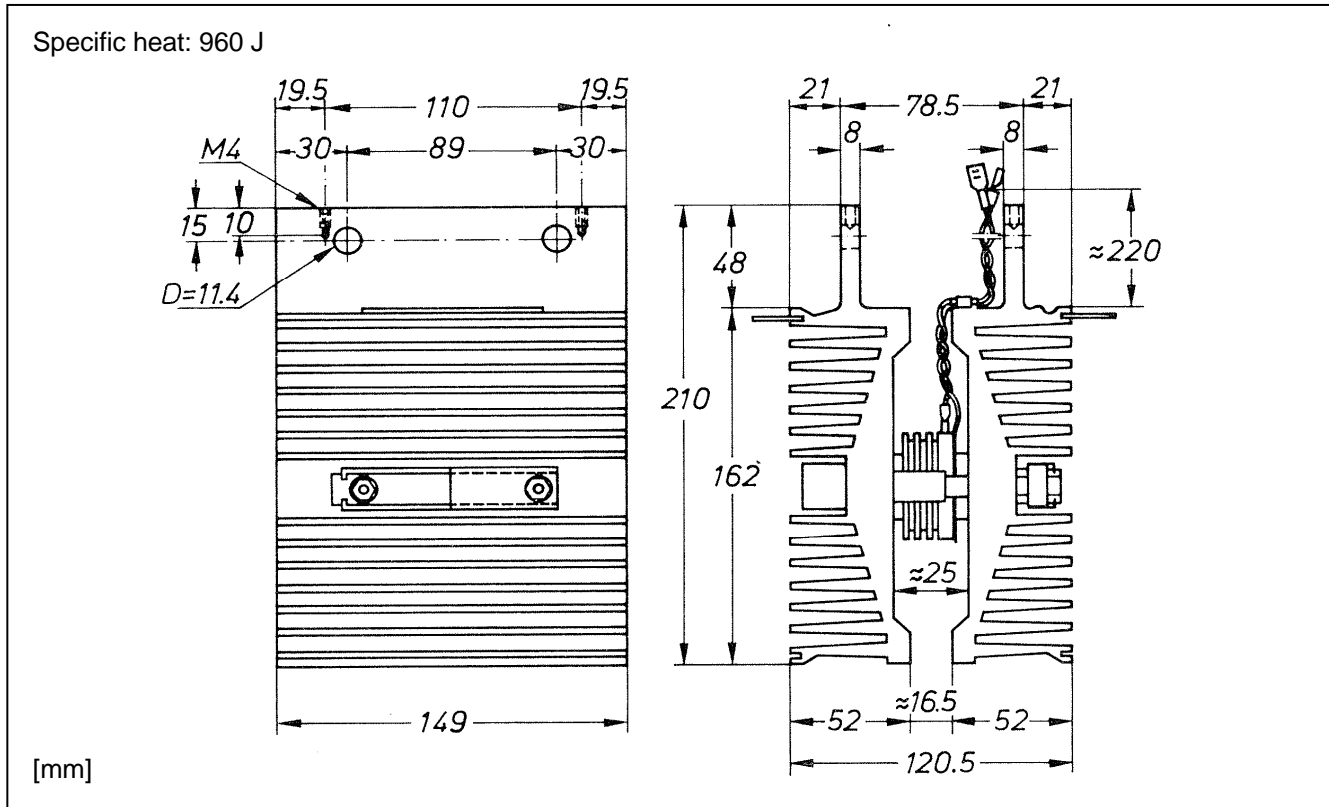
Air Cooled Heat sink

5SAA21V9000, 5SAA21V8500

Type YAP 3-05

Air cooled heat sink for double sided cooling of disc housing thyristors and diodes, diameter 40 - 75 mm.

Part number	Max contact diameter	Weight	R _{thHA} at air flow measured with specified device contact diameter			R _{thHA} at power dissipation measured with specified device contact diameter			Recommended mounting clamp
			Forced air cooling			Convective air cooling			
			mm	kg	K/kW	dm ³ /s	mm	K/kW	
5SAA21V9000	19	3.7	90	100	19	510	150	19	5SAC10V1600
5SAA21V8500	50	3.6	85	100	47	485	150	47	5SAC10V1600



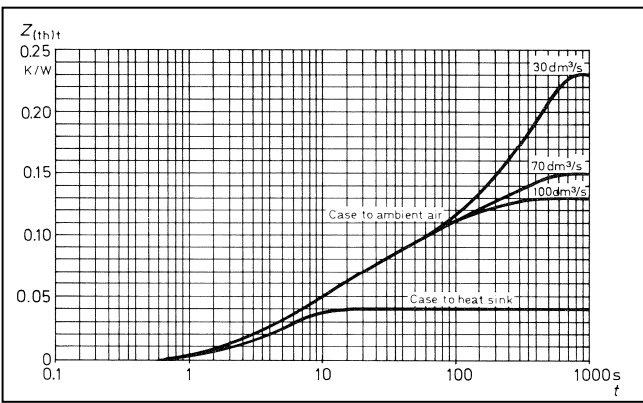


Fig. 1 Transient thermal impedance, $Z_{(th)t}$. Case to ambient air at different air-flow rates. Pole piece \varnothing 19 mm

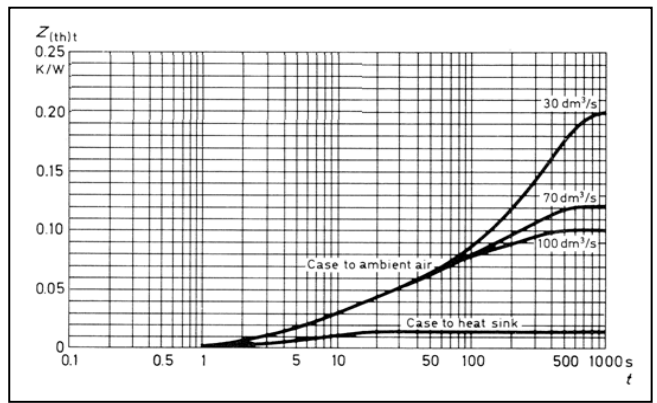


Fig. 2 Transient thermal impedance, $Z_{(th)t}$. Case to ambient air at different air-flow rates. Pole piece \varnothing 34 mm

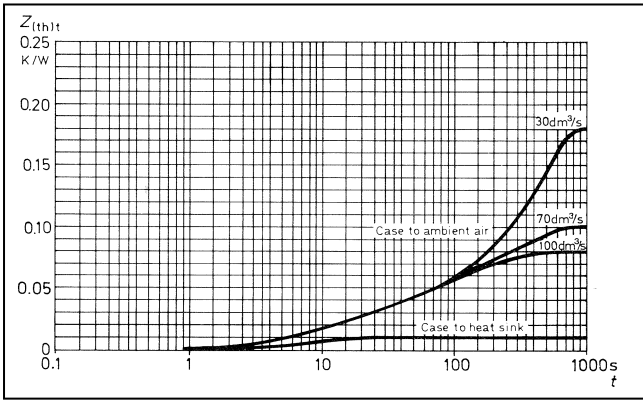


Fig. 3 Transient thermal impedance, $Z_{(th)t}$. Case to ambient air at different air-flow rates. Pole piece \varnothing 47 mm

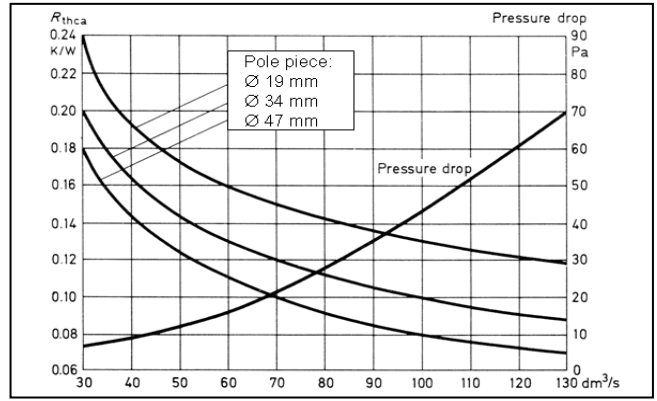


Fig. 4 Thermal resistance R_{thca} . Case to ambient air and static pressure drop vs flow of cooling air.

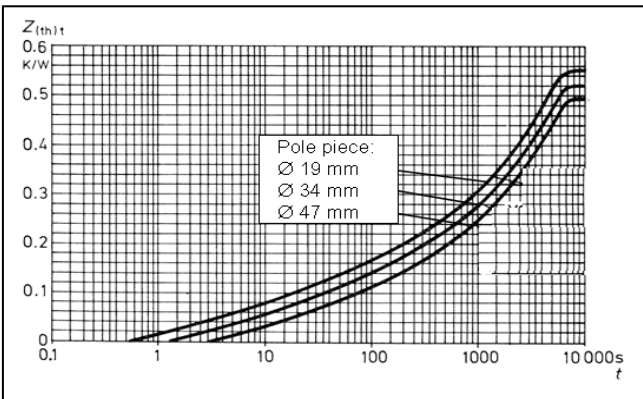


Fig. 5 Convection cooling. Transient thermal impedance $Z_{(th)t}$. Case to ambient air. Power loss 150 W.

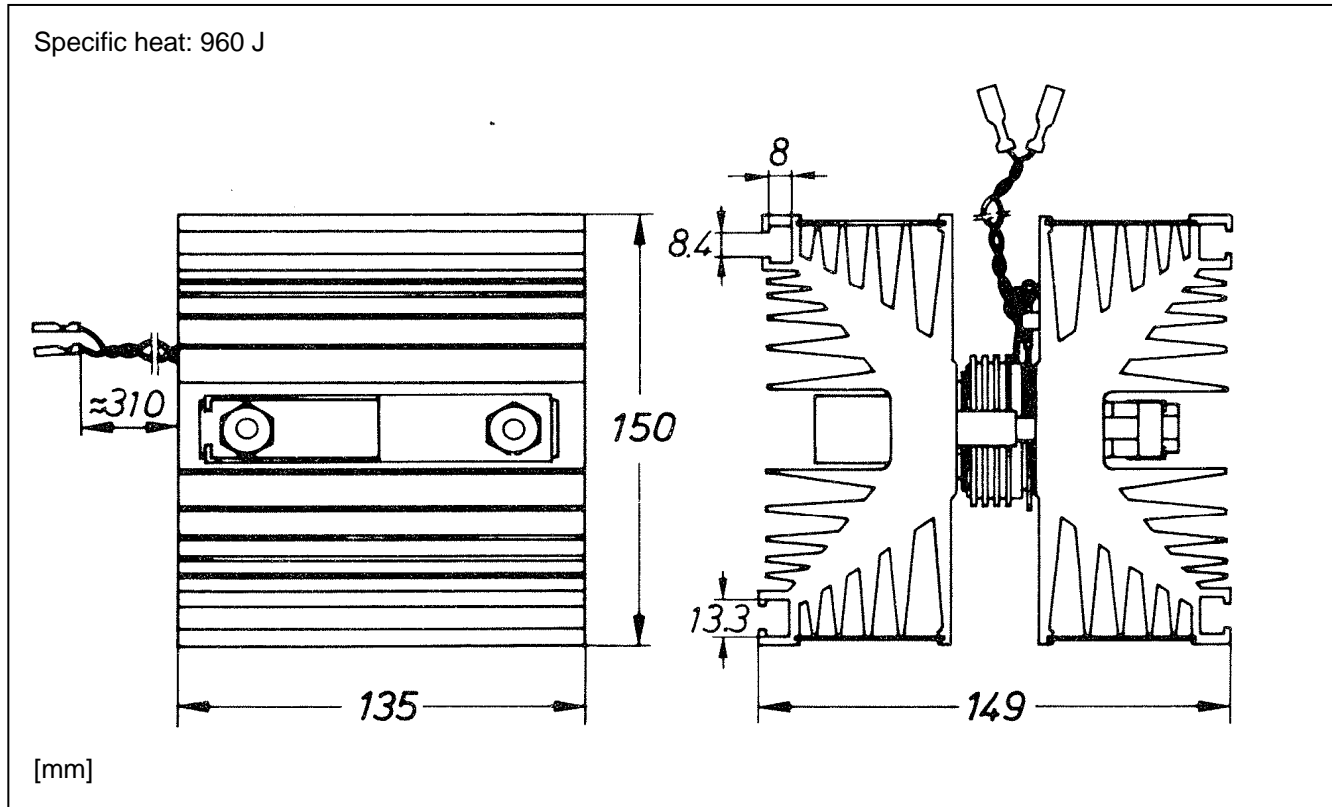
Air Cooled Heat sink

5SAA15V9000, 5SAA15V8500

Type YAP 6-01

Air cooled heat sink for double sided cooling of disc housing thyristors and diodes, diameter 40 - 75 mm.

Part number	Max contact diameter	Weight	R _{thHA} at air flow measured with specified device contact diameter			R _{thHA} at power dissipation measured with specified device contact diameter			Recommended mounting clamp
			Forced air cooling			Convective air cooling			
			K/kW	dm ³ /s	mm	K/kW	W	mm	
5SAA15V9000	19	3.4	90	100	19	510	150	19	5SAC10V1600
5SAA15V8500	50	3.3	85	100	47	485	150	47	5SAC10V1600



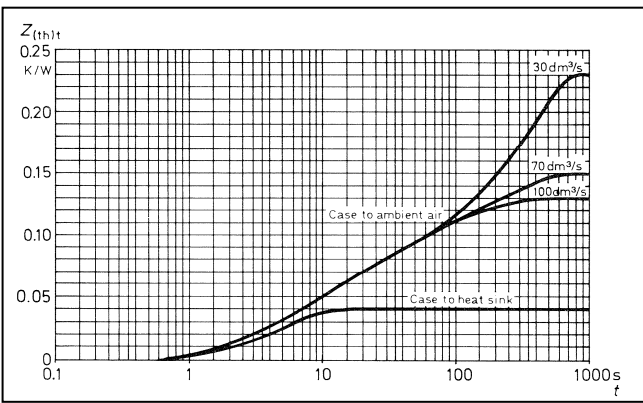


Fig. 1 Transient thermal impedance, $Z_{(th)t}$. Case to ambient air at different air-flow rates. Pole piece \varnothing 19 mm

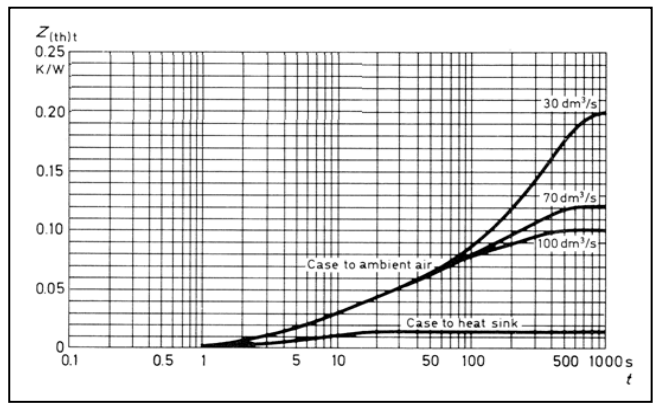


Fig. 2 Transient thermal impedance, $Z_{(th)t}$. Case to ambient air at different air-flow rates. Pole piece \varnothing 34 mm

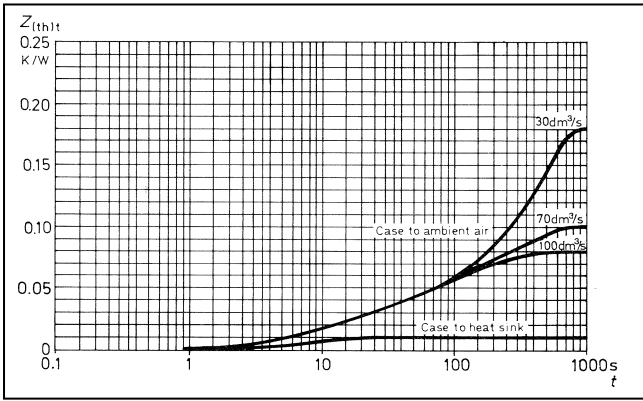


Fig. 3 Transient thermal impedance, $Z_{(th)t}$. Case to ambient air at different air-flow rates. Pole piece \varnothing 47 mm

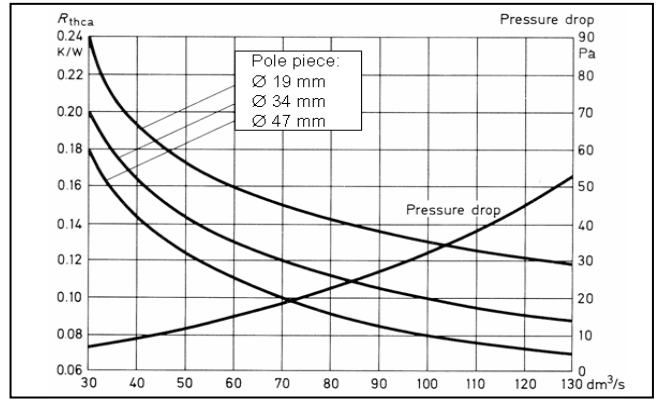


Fig. 4 Thermal resistance R_{thca} . Case to ambient air and static pressure drop vs flow of cooling air.

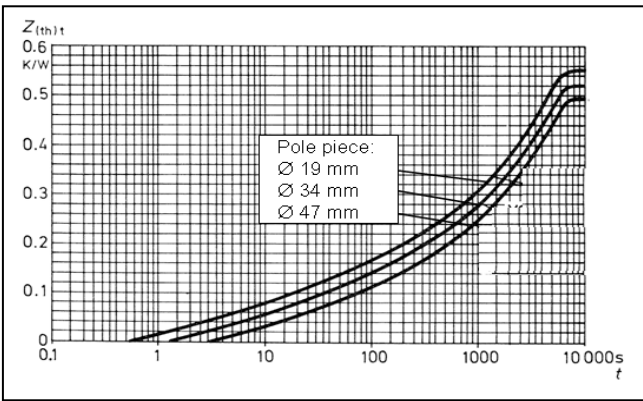


Fig. 5 Convection cooling. Transient thermal impedance $Z_{(th)t}$. Case to ambient air. Power loss 150 W.

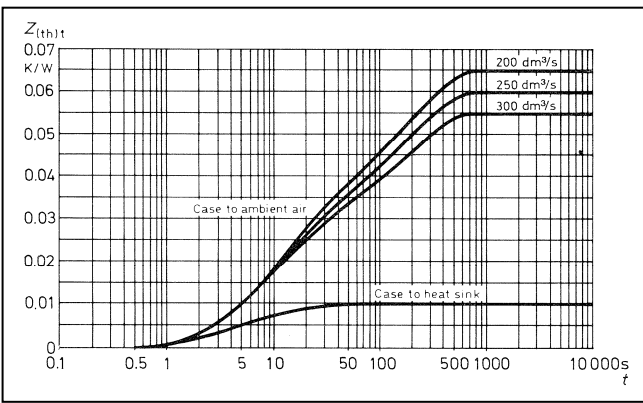


Fig. 1 Transient thermal impedance, $Z_{(th)t}$. Case to ambient air at different air-flow rates. Pole piece \varnothing 47 mm.

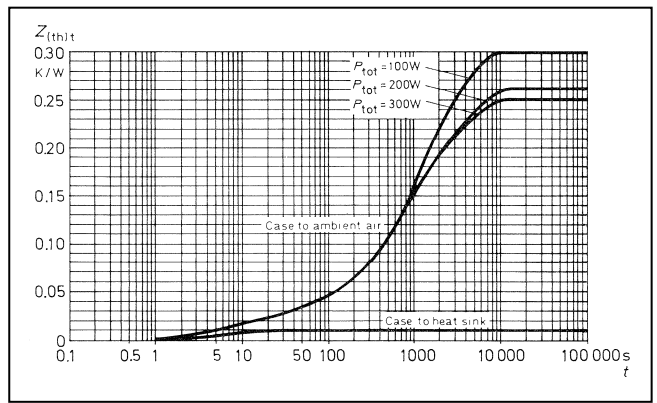


Fig. 2 Convection cooling. Transient thermal impedance $Z_{(th)t}$. Case to ambient air for different power losses. Pole piece 47 mm.



Fig. 3 Thermal resistance R_{thca} . Case to ambient air and static pressure drop vs flow of cooling air. Pole piece \varnothing 47 mm.

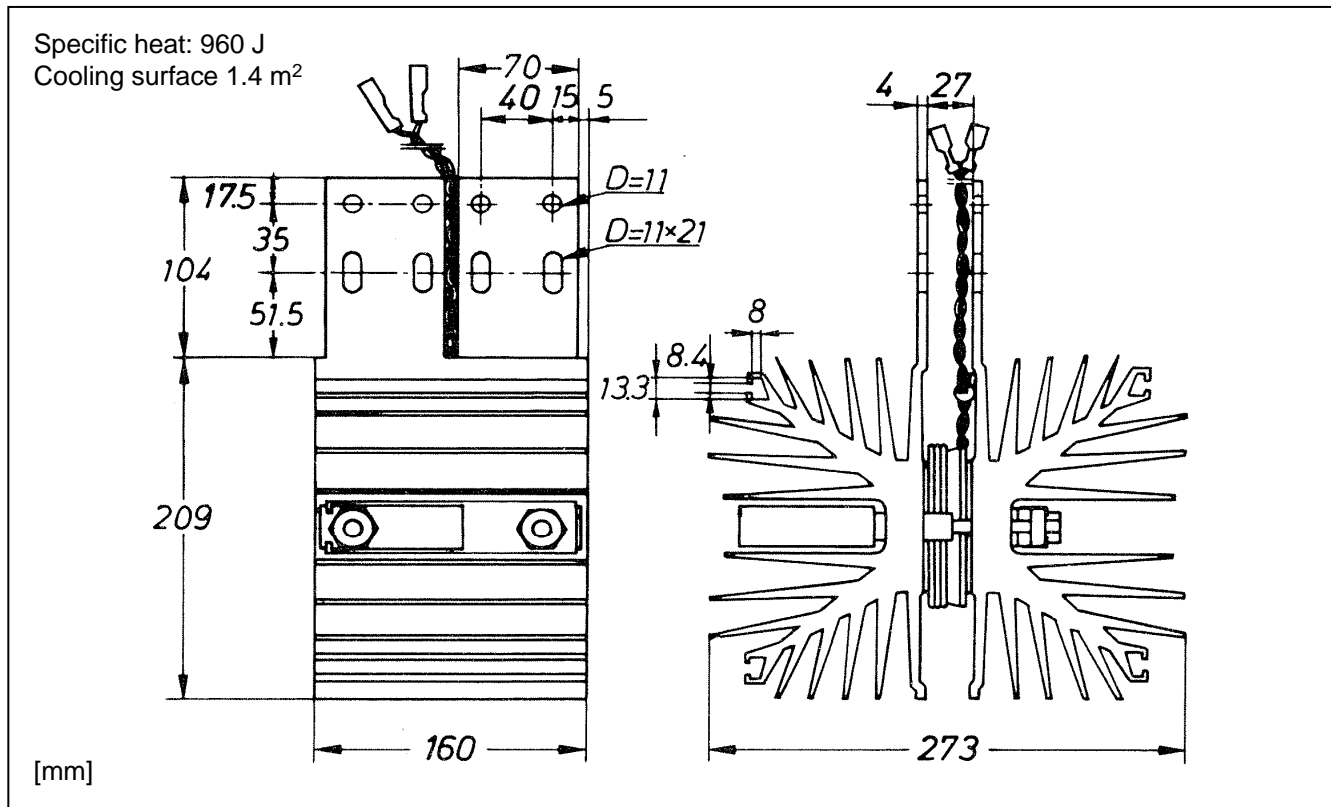
Air Cooled Heat sink

5SAA21V3500

Type YAP 8-03

Air cooled heat sink for double sided cooling of disc housing thyristors and diodes, diameter 100 - 110 mm.

Part number	Max contact diameter	Weight	R _{thHA} at air flow measured with specified device contact diameter			R _{thHA} at power dissipation measured with specified device contact diameter			Recommended mounting clamp
			Forced air cooling			Convective air cooling			
			mm	kg	K/kW	dm ³ /s	mm	K/kW	
5SAA21V3500	80	8.2	35	300	78	230	300	78	5SAC13V5000



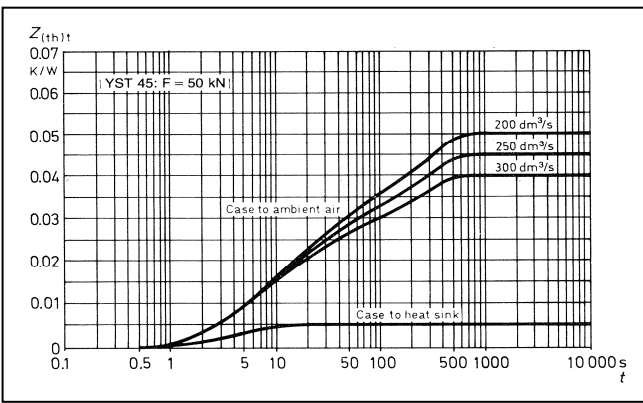


Fig. 1 Transient thermal impedance, $Z_{(th)t}$. Case to ambient air at different air-flow rates. Pole piece $\text{Ø } 78 \text{ mm}$.

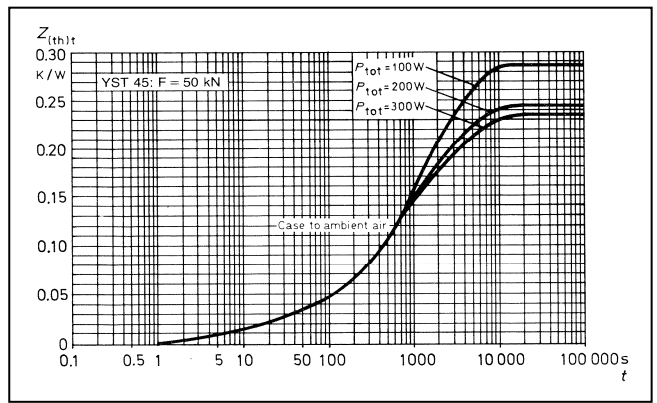


Fig. 2 Convection cooling. Transient thermal impedance $Z_{(th)t}$. Case to ambient air for different power losses. Pole piece 78 mm .

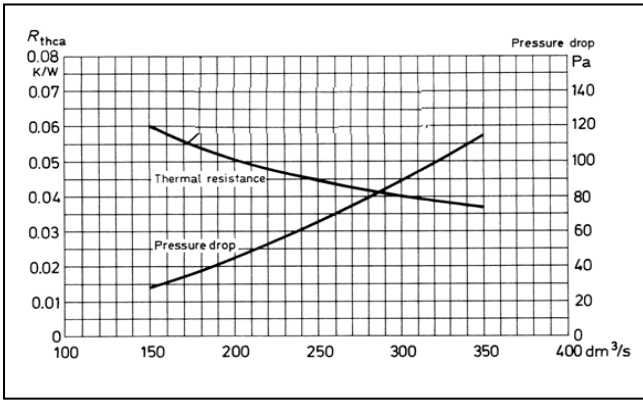


Fig. 3 Thermal resistance R_{thca} . Case to ambient air and static pressure drop vs flow of cooling air. Pole piece $\text{Ø } 78 \text{ mm}$.